# PACE1757M/ME COMPLETE EMBEDDED CPU SUBSYSTEM

## FEATURES

Implements complete MIL-STD-1750A ISA including optional MMU, MFSR, and BPU functions.

- Two throughput options: P1757M 2.5MIPS USAF Dais Mix (Inc.Flt.Pt.)@40 MHz P1757ME 3.6MIPS USAF Dais Mix (Inc.Flt.Pt.)@40 MHz
- All MIL-STD-1750A data formats and address types implemented.
- P1757ME includes additional matrix and vector instructions to enhance throughput in navigation, DSP transcendental and other complex alorithms.
- Error detection and correction and parity bit provided.
- Separate high drive external address & data busses.
- 10MHz data rate at 40MHz CPU clock
- System support functions included:
  - Arbitrator for use in tightly coupled multiprocessor design. Bus control provided to aid in implementation of multi-processor systems.
  - MIL-STD-1750A timers A & B, programmable watch dog timer and programmable bus time-out function.
  - Start up ROM support per MIL-STD-1750A.
  - DMA support for logical and physical memory addresses.

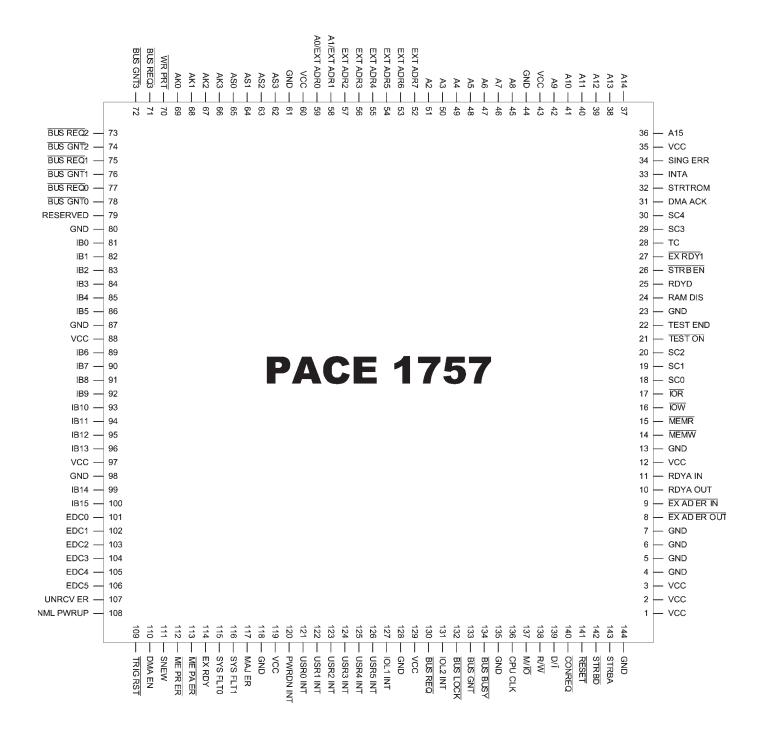
- Programmable memory and I/O data wait state generation permits up to four different memory speeds in the same system.
- Programmable address wait states.
- Sixteen levels of interrupts are provided per MIL-STD-1750A. Interrupts can be either edge- or level-sensitive.
- Fault detection and handling
  - Programmable detection of unimplemented memory or illegal I/O addresses.
  - Full implementation of MIL-STD-1750A fault register.
  - External address error detection.
- Testability and diagnostics.
  - First falling address and data registers.
  - Built in test runs automatically at power on and after each reset. All hardware blocks and external busses examined. Hardware pass/fail for catastrophic failures. Status register indicates failed test.
  - Console operating mode which allows operator to examine and change contents of registers within the CPU, any system memory location, or the I/O subsystems.
- Single 144-pin Quad straight lead or Gullwing 1.5 square inches of board surface.
- Operating temperature range -55 to +125°C; single 5V ± 10% V<sub>CC</sub> power supply; power dissipation < 1.9W (worst case at 40 MHz).</p>

# GENERAL DESCRIPTION

All functions required for a complete MIL-STD-1750A embedded CPU subsystem are in this single VLSI microcircuit occupying 1.5 square inches of board space with less than 1.9 watts of power dissipation at 40 MHz. Pyramid's P1757M/ME is a complete, single package, 3.6 MIPS subsystem solution to embedded processor requirements. The PACE 1757M uses the application-proven PACE 1750A microprocessor, the PACE 1753, and the PACE 1754. The PACE1757ME uses the enhanced PACE 1750AE microprocessor, which has additional instructions that provide high throughput for transcendental functions, navigational algorithms, and DSP functions. The PACE 1750AE is an architectural enhancement of the PACE 1750A.



Document # MICRO-10 REV B



## AC/DC ELECTRICAL SPECIFICATIONS

## MAXIMUM RATINGS

(Above which the useful life may be impaired)

Storage Temperature	-65°C to +150°C
Ambient Temperature with Power	-55°C to +125°C
VCC Pin Potential to Ground Pin	-0.5V to 7.0V
Input Voltage	-0.5V to V <sub>CC</sub> + 0.5V
Input Current	-30 mA to 5 mA
Voltage Applied to Inputs	-0.5V to V <sub>CC</sub> + 0.5V
Current Applied to any Output	100 mA
Power Dissipation	2.5 Watts
θ <sub>JA</sub>	35°C/W

## **RECOMMENDED OPERATING CONDITIONS**

Grade	Case Temperature GND		V <sub>CC</sub>	
Military	-55°C to +125°C	0V	5.0V ± 10%	

## DC ELECTRICAL SPECIFICATIONS

(Over recommended operating conditions)

Symbol	Parameter	Min	Тур.	Max	Unit	Conditions
V <sub>IH</sub>	Input HIGH Level	2.0		V <sub>CC</sub> +0.5	V	
V <sub>IL</sub>	Input LOW Level <sup>2</sup>	-0.5		0.8	V	
V <sub>CD</sub>	Input clamp diode voltage			-1.2	V	I <sub>IN</sub> =-18mA
						V <sub>CC</sub> =Min
V <sub>OH</sub>	Output HIGH Voltage	2.4			V	I <sub>OH</sub> =-8mA
		V <sub>CC</sub> -0.2			V	I <sub>OH</sub> =-300µА
						V <sub>CC</sub> =Min
V <sub>OL</sub>	Output LOW Voltage			0.5	V	I <sub>OL</sub> =8mA
	Except A <sub>0</sub> -A <sub>15</sub> ,					
	EXT ADR <sub>0</sub> -EXT ADR <sub>7</sub>			0.2	V	Ι <sub>ΟL</sub> =300μΑ
						V <sub>CC</sub> =Min
	Output LOW Voltage			0.5	V	I <sub>OL</sub> =20mA
	A <sub>0</sub> -A <sub>15</sub> ,					
	EXT ADR <sub>0</sub> -EXT ADR <sub>7</sub>			0.2	V	Ι <sub>ΟL</sub> =300μΑ
						V <sub>CC</sub> =Min
I <sub>IH</sub>	Input HIGH Current except			10	μA	V <sub>IN</sub> =V <sub>CC</sub>
	$IB_0-IB_{15}$ , $EDC_0-EDC_5$ , $\overline{BUS}$					V <sub>CC</sub> =Max
	BUSY, BUS LOCK,					
	EXT ADR <sub>0</sub> -EXT ADR <sub>7</sub>					
	Input HIGH Current IB <sub>0</sub> -IB <sub>15</sub> ,			50	μA	$V_{IN} = V_{CC}$
	$EDC_0$ - $EDC_5$ , $\overline{BUS BUSY}$ ,					V <sub>CC</sub> =Max
	BUS LOCK,					
	EXT ADR <sub>0</sub> -EXT ADR <sub>7</sub>					



## DC ELECTRICAL SPECIFICATIONS (Continued)

(Over recommended operating conditions)

Symbol	Parameter		Min	Тур.	Max	Unit	Conditions
I <sub>IL</sub>	Input LOW current except IB <sub>0</sub> -IB <sub>1</sub>	<sub>15</sub> , EDC <sub>0</sub> -					V <sub>IN</sub> =GND
	EDC5, BUS BUSY, BUS LOCK				-10	μA	V <sub>CC</sub> =Max
	EXT ADR <sub>0</sub> -EXT ADR <sub>7</sub> , TEST ON						
	Input LOW current TEST ON				-500		V <sub>IN</sub> =V <sub>CC</sub>
	Input LOW current IB <sub>0</sub> -IB <sub>15</sub> , EDC	<sub>0</sub> -EDC <sub>5</sub> ,					V <sub>CC</sub> =Max
	BUS BUSY, BUS LOCK,				-50	μA	
	EXT ADR <sub>0</sub> -EXT ADR <sub>7</sub>						
I <sub>OZH</sub>	Output 3-state current Except SI	NGERR,			50		V <sub>OUT</sub> =2.4V
	STRBA	OTDDA				μA	V <sub>CC</sub> =Max
	Output 3-state current SINGERR Output 3-state current Except S				500		
I <sub>OZL</sub>		IKDU			-50	μA	V <sub>OUT</sub> =0.5V
	Output 3-state current STR BD				-500		V <sub>CC</sub> =Max
I <sub>CCQC</sub>	Quiescent Power Supply Current						$V_{IN} < 0.2V$ or
	(CMOS Input Levels)				80	80 mA	> V <sub>CC</sub> -0.2V, f=0Hz
							Outputs open
							V <sub>CC</sub> =Max
ICCQT	Quiescent Power Supply Current						V <sub>IN</sub> =3.4V, All inputs,
	(TTL Levels)				210	mA	f=0Hz
							Outputs open
							V <sub>CC</sub> =Max
ICCD	Dynamic Power Supply Current	f=20 MHz			280		$V_{IN} < 0.8V \text{ or } > 3.4V,$
TTL		f=30 MHz f=35 MHz			310	mA	Outputs open
		f=40 MHz			325		V <sub>CC</sub> =Max
					340		
I <sub>CCD</sub>	Dynamic Power Supply Current	f=20 MHz			150		V <sub>IN</sub> < 0.2V or
		f=30 MHz			180		> V <sub>CC</sub> -0.2V
		f=35 MHz			195 210	mA	Outputs open,
		f=40 MHz					V <sub>CC</sub> =Max
l <sub>os</sub>	Output Short Circuit Current <sup>1</sup>		<u> </u>				V <sub>OUT</sub> =GND
	(one output shorted at a time)		-25			mA	V <sub>CC</sub> =Max
C <sub>IN</sub>	Input Capacitance <sup>3</sup>			5		pF	Inputs Only
C <sub>OUT</sub>	Output Capacitance <sup>3</sup>			9		pF	Outputs (includes I/O
				Ŭ		יץ	Buffers)

Note 1: Duration of the short should not exceed one second.

Note 2:  $V_{IL}$ =-3.0V for pulse widths less than or equal to 20ns.

Note 3: This parameter is set by design and not tested.

## TIMING GENERATOR STATE DIAGRAMS

Two separate and almost independent state diagrams may be used to describe the PACE1757M machine cycle.

The Execution Unit performs according to a cycle of three state represented by Diagram A (the A machine) and the External Bus Unit follows a minimum cycle of four states, indicated in Diagram B (the B machine).

Referring to Diagram A, the paths are defined as follows for the Execution Unit:

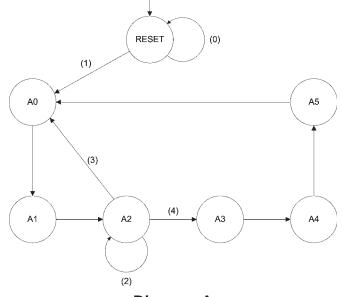
- (0) External Reset true
- (1) External Reset false
- (2) ALU wait or Bus wait.
- (3) ALU Branch false
- (4) ALU Branch true

Diagram B defines the paths for the External Bus as follows:

- (0) External Reset false
- (8) Bus Req. false
- (9) Bus Req. true and Bus Av. true
- (10) Bus Req. true and Bus Av. false
- (11) Bus Av. false
- (12) Bus Av. true
- (13) RDYA false
- (14) RDYA true
- (16) RDYD false
- (17) RDYD true and Bus Req. true and Bus Av. true
- (18) RDYD true and Bus Req. false
- (19) RDYD true and Bus Req. true and Bus Av. false
- (20) Bus Req. true and Bus Av. true

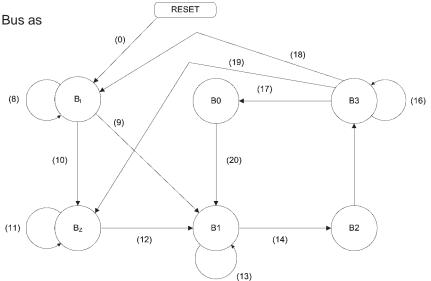
### NOTE:

Bus  $A_V$  = Bus grant and Bus not busy and Bus not locked.



RESET







## DIFFERENCES BETWEEN THE PACE1757M AND PACE1757ME

The PACE1757ME, which uses the P1750AE CPU, achieves a 41% boost in performance (in clock cycles) over the PACE1757M, which uses the P1750A CPU. This reduction in clocks per instruction is because of three architectural enhancements:

1. The inclusion of a 24 x 24 Multiply Accumulate (MAC) array.

2. A reduction in non-bus cycles to 2 clocks (bus cycles remain at 4 clocks to maintain full compatibility with CPU's peripheral chips).

3. Branch calculation logic.

The table below shows how the MAC improves all multiply operations - both integer and floating point - by 477% to 760%

	PACE	1750AE	PACE	Gain	
Instruction	Clocks	Execution Time (40 MHz)	Clocks	Execution Time (40 MHz)	# Clocks (%)
Integer Add/Sub	4	100ns	4	100ns	_
Double Precision Integer Add/Sub	6	150ns	9	225ns	50
Integer Multiply	4	100ns	23	575ns	575
Double Precision Integer Add/Sub	9	225ns	69	1725ns	760
Floating Add/Sub	18	450ns	28	700ns	55
Extended Floating Add/Sub	34	850ns	51	1225ns	50
Floating Multiply	9	225ns	43	1075ns	477
Extended Floating Point Multiply	17	425ns	96	2400ns	564
Branch (Taken)	8	200ns	12	300ns	50
Branch (Not Taken)	4	100ns	4	100ns	
Flt'g' Point Polynomial Step (Mul+Add/Sub)	27	675ns	71	1775ns	263
Ext Flt'g' Point Polynomial Step (Mul/Sub)	51	1275ns	147	3675ns	2400
DAIS Mix (MIPS)		3.56		2.52	41/59

## PACE1757ME BUILT-IN FUNCTIONS

A core set of additional instructions have been included in the PACE1757ME. These instructions use the Built-In Function (BIF) opcode space. The objective of these new opcodes is to enhance the performance of the PACE in critical application areas such as navigation, DSP, transcendentals and other LINPAK and matrix type instructions. Below is a list of the BIFs and their execution times (N = the number of elements in the vector being processed).

Instruction	Mnemonic	Address Mode	Number of Clocks	Notes
Memory Parametric Dot Product - Single	VDPS	4F3(RA)	10 + 8 • N	Interruptable
Memory Parametric Dot Product - Double	VDPD	4F1(RA)	10 + 16 • N	Interruptable
3 x 3 Register Dot Product	R3DP	4F03	6	
Double Precision Multiply Accumulate	MACD	4F02	8	
Polynomial POLY	4F06	7 • N -2		
Clear Accumulator CLAC	4F00	4		
Store Accumulator (32-Bit)	STA	4F08	7	
Store Accumulator (48-Bit)	STAL	4F04	11	
Load Accumulator (32-Bit)	LAC	4F05	9	
Load Accumulator Long (48-Bit)	LACL	4F07	9	
Move MMU Page Block	MMPG	4F0F	16 + 8 • N	Priveleged
Load Timer A Reset Register	LTAR	4F0D	4	
Load Timer B Reset Register	LTBR	4F0E	4	

## TIMING GENERATOR STATE DIAGRAMS

Two separate and almost independent state diagrams may be used to describe the PACE1757ME machine cycle.

The Execution Unit performs according to a cycle of three states represented by Diagram A (the A machine) and the External Bus Unit follows a minimum cycle of four states, indicated in Diagram B (the B machine).

Referring to Diagram A, the paths are defined as follows for the Execution Unit:

- (0) External Reset true
- (1) External Reset false
- (2) ALU wait or Bus wait.
- (3) ALU Branch false
- (4) ALU Branch true

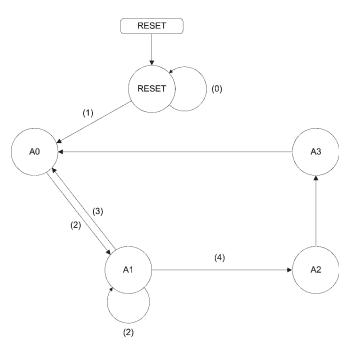
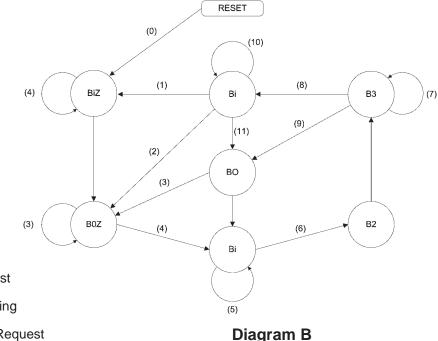




Diagram B defines the paths for the External Bus as follows:

- (0) External Rest false
- (1) No Internal Bus Req.
- (2) Internal Bus Req.
- (3) Bus Busy or No Bus Grant
- (4) Bus Grant and Not Busy or Bus Locked by CPU
- (5) RDYA false
- (6) RDYA true
- (7) RDYD false
- (8) RDYD true, and no Internal Bus Request
- (9) RDYD true, Internal Bus Request pending
- (10) Bus Locked by CPU and No Internal Request
- (11) Bus Locked by CPU Internal Req.



NOTE: Bus  $A_V$  = Bus grant and Bus not busy and Bus not locked.

## SIGNAL PROPAGATION DELAYS

i.		20 MHz		30 MHz		35 MHz		40 MHz	
Symbol	Description	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
TC(BR)	BUS REQUEST		33		25		22		22
TC(BR) <sub>H</sub>			33		25		22		22
TBG <sub>V</sub> (C)	BUSGRANT - Setup	5		5		5		5	
TC(BG) <sub>x</sub>	BUSGRANT - Hold	5		5		5		5	
TC(BB)	BUS BUSY		25		24		22		20
TC(BB) <sub>H</sub>			25		20		18		17
TBB <sub>V</sub> (C)	BUS BUSY - Setup	5		5		5		5	
TC(BB) <sub>x</sub>	BUS BUSY - Hold	5		5		5		5	
TC(BL)	BUSLOCK		30		25		23		21
TC(BL) <sub>H</sub>			30		20		19		17
TBL <sub>v</sub> (C)	BUS LOCK - Setup	5		5		5		5	
TC(BL) <sub>x</sub> (IN)	BUS LOCK - Hold	5		5		5		5	
TC(ST) <sub>v</sub>	M IO		30		25		23		20
	R/W		30		25		23		20
	AS0:AS3, AK0:AK3, D/Ī		25		20		20		20
TC(ST) <sub>x</sub>	M 10, R/W, AS0:AS3, AK0:AK3, D/1	0		0	1	0	1	0	
TC(SA) <sub>H</sub>	STRBA		22		17		16		16
TC(SA)			22		17		16		16
TSA, (IBA) <sub>x</sub>	Address Hold from STRBA(L)	5		5		5		5	
TRA <sub>V</sub> (C)	RDYA - Setup	5		5		5		5	
TC(RA) <sub>x</sub>	RDYA - Hold	5		5		5		5	
TC(SDW)	STRBD		22		17		16		14
TC(SD) <sub>H</sub>			22		17		16		14
TFC(SDR)			22		17		16		14
TIBD <sub>x</sub> (SDR) <sub>H</sub>		0		0		0		0	
TSDW <sub>H</sub> (IBD) <sub>X</sub>		30		25		21		17	
TSD <sub>L</sub> (SD) <sub>H</sub> (Write)		40		26		23		20	
TRD(RD) <sub>x</sub>	RDYD - Setup	5		5		5		5	
TC(RD) <sub>x</sub>	RDYD - Hold	5		5		5		5	
TC(IBA) <sub>V</sub>	IB0:IB15		30		25		23		20
TFC(IBA) <sub>x</sub>		0		0		0		0	
TIBDR <sub>V</sub> (C)	- Setup	5		5		5		5	
TC(IBD) <sub>x</sub> (Read)	- Hold	5		5		5		5	
TC(IBD) <sub>x</sub> (Write)	DATAVALID (OUT)	0		0		0		0	
TFC(IBD) <sub>v</sub>			30		25		23		20
TC(SNW)	SNEW		30		26		24		22
TFC(TGO)	TRIGORST		30		26		24		22
TRST, (DMA EN),	DMA ENABLE		40		35		33		30
TC(DME)			40		35		33		30
TFC(NPU)	NORMAL POWER-UP		40		35		33		30
TC(ER)	CLK TO MAJER (UNRCV ER)		60		50		47		45
TRST <sub>L</sub> (NPU)	RESET		50		40		35		30
TREQ <sub>V</sub> (C)	CON REQ	0		0		0		0	
TC(REQ) <sub>x</sub>		10		10		10		10	
TF <sub>V</sub> (BB) <sub>H</sub>	LEVEL SENSITIVE FAULTS	5		5	1	5	1	5	
TBB <sub>H</sub> (F) <sub>X</sub>		5		5		5		5	
TIR <sub>V</sub> (C)	IOL 1/2 INT. USR INT (0:5) - Setup	0		0	1	0	1	0	
TC(IR) <sub>x</sub>	PWRDN INT, LEVEL SENSITIVE - HOLD	10		10		10		10	
TRST <sub>L</sub> (TRST <sub>H</sub> )	RESET PULSE WIDTH	25	l	20		18		15	
TC(XX) <sub>z</sub>	CLK TO TRI-STATE	l	22		17		15		13

Note 1: Units = ns

		20	MHz	30 MHz		35 MHz		40 MHz	
Symbol	Description	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
TD/I(EXT ADR) <sub>v</sub>	MMU Cache Hit		25		23		23		23
TSTRBD(EXT ADR ER)	External Address Error		25		20		18		16
TIBD <sub>V</sub> (EDC GEN) <sub>V</sub>	Error Correction Write Cycle		30		25		24		23
TC(GNT)	Arbiter Priority Transition		35		25		22		18
TC(RDYA)	Address Ready		30		25		21		17
TIBDIN(MEM PAR ER)	Parity Mode		34		30		28		25
TC(MEM PRT ER)	Memory Protect Error		50		45		43		40
TSTRBD (WR PROT)	Write Protect Cache Hit		25		20		18		16
TC(WR PROT)I	Write Protect Cache Miss		25		22		20		18
TD/I(PROT FLAG)	Cache Hit (BPU Protection Error)		40		45		42		40
TD/I(PROT FLAG)	Cache Hit (MMU Key-Lock Error)		40		35		33		30
TC(PROT FLAG)	Cache Hit (BPU Protection Error)		25		35		33		30
TC(PROT FLAG)	Cache Hit (MMU Key-Lock Error)		25		20		20		20
TC(EXT ADR) <sub>V</sub>	Clock to EXT Address Valid (Miss)		32		30		27		23
TFC(IB OUT) <sub>V</sub>	Clock to EXT Address Valid (Miss)		30		25		25		25
TEX RDY1(RDYD)	Ready Data		28		24		23		21
TEX RDY(RDYD)	Ready Data		16		13		12.5		11.5
TC (RDYD) <sub>v</sub>	Ready Data		28		22		19		16
TSTRBAh(Å) <sub>v</sub>	Address Valid		29		21		20		19
TIBA <sub>V</sub> (A) <sub>V</sub>	Address Valid		31		22		21		20
TFC (R) <sub>L</sub>	Read Strobes		24		18		15		12
TSTRBD <sub>H</sub> (R) <sub>H</sub>	Read Strobes		24		18		15		12
TSTRBD <sub>H</sub> (W) <sub>L</sub>	Write Strobes		26		20		18		15
TSTRBD <sub>L</sub> (W) <sub>H</sub>	Write Strobes		26		20		18		15
TSTRBD(STRTROM)	Start-Up ROM		26		20		18		15
TC(TIM CLK)	Timer Clock		30		25		23		20
TEXT AD(FC B3)	Extended Address Set-Up	10		10		10		10	
TF(F), TI(I)	Edge Sensitive Pulse Width	5		5		5		5	
tr, tf	Clock Rise and Fall Time		5		5		5		5

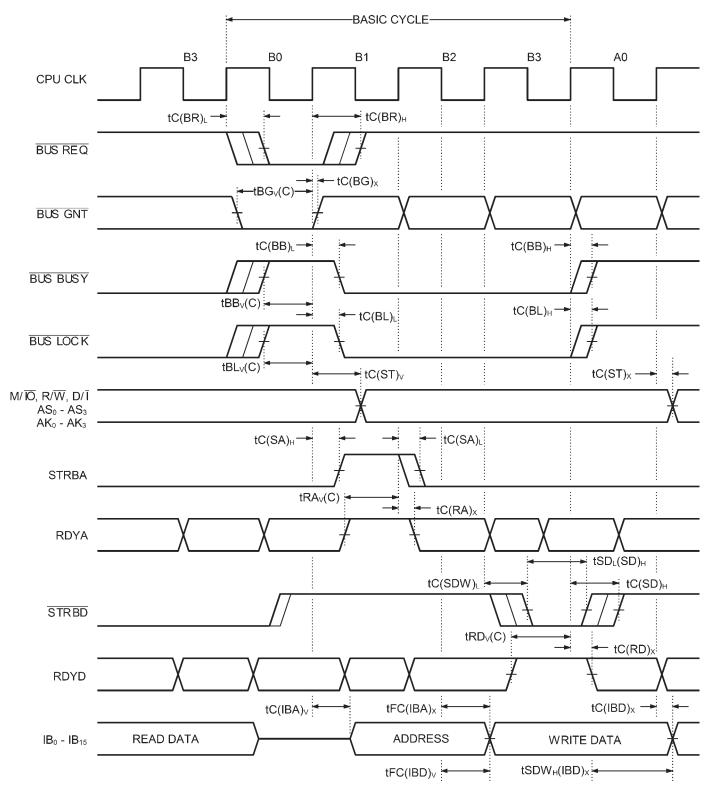
### SIGNAL PROPAGATION DELAYS (cont'd)

Units = ns

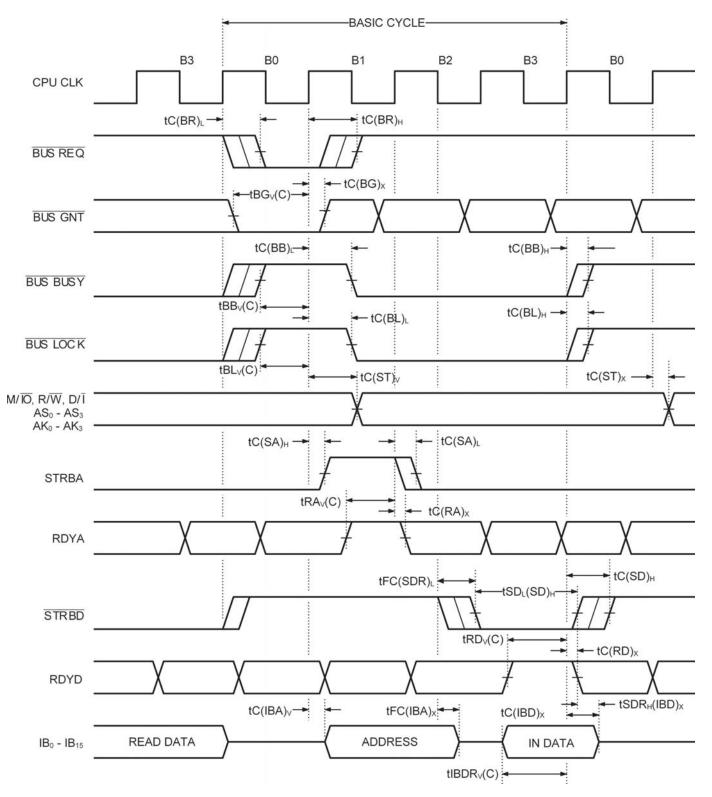
#### Note

All timing parameters are composed of Three elements. The first "T" stands for timing. The second represents the "from" signal. The third in parentheses indicates "to" signal. When the CPU clock is one of the signal elements, either the rising edge "E" or the falling edge "FC" is referenced. When other elements are used, an additional suffix indicates the final logic level of the signal. "L" - low level, "H" - high level, "V" - valid, "Z" - high impedance, "X" - don't care, "LH" - low to high, "ZH" - high impedance to high, "R" - read cycle, and "W" - write cycle.

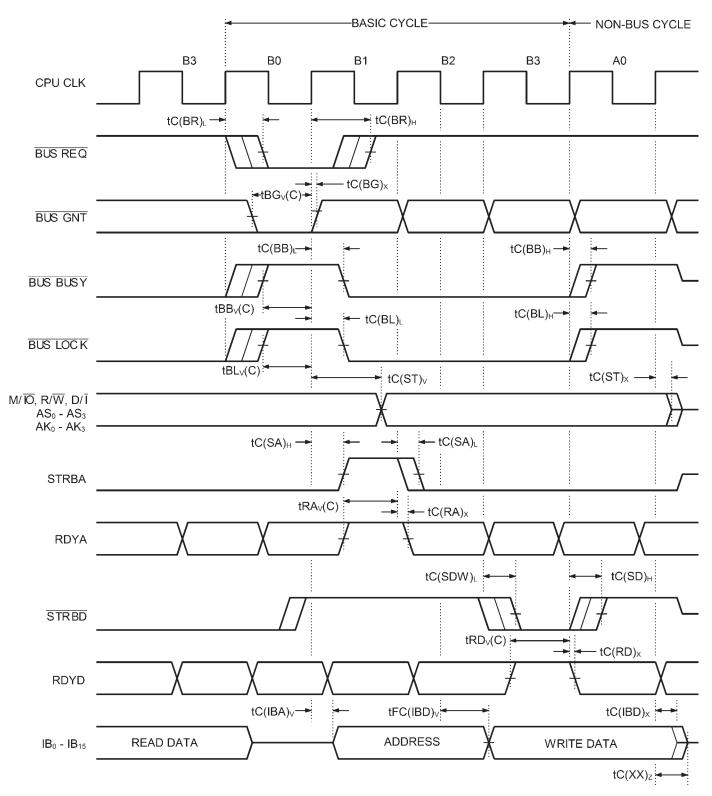
## MINIMUM WRITE BUS CYCLE TIMING DIAGRAM

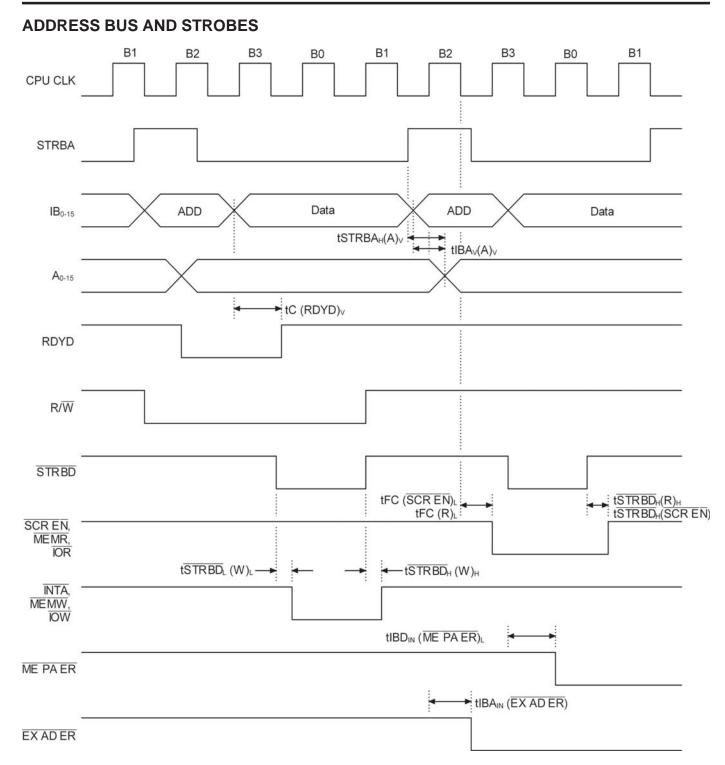


## MINIMUM READ BUS CYCLE TIMING DIAGRAM



## MINIMUM WRITE BUS CYCLE, FOLLOWED BY A NON-BUS CYCLE, TIMING DIAGRAM



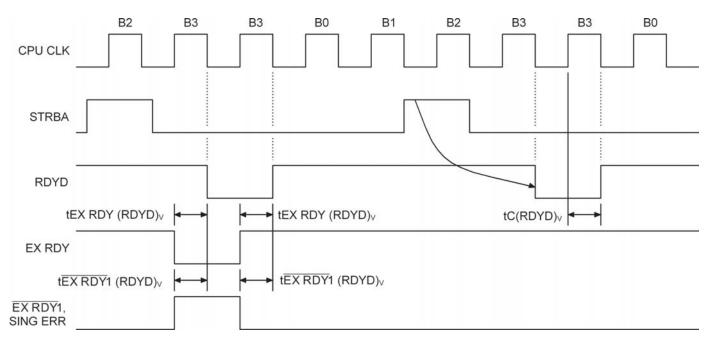


#### Note:

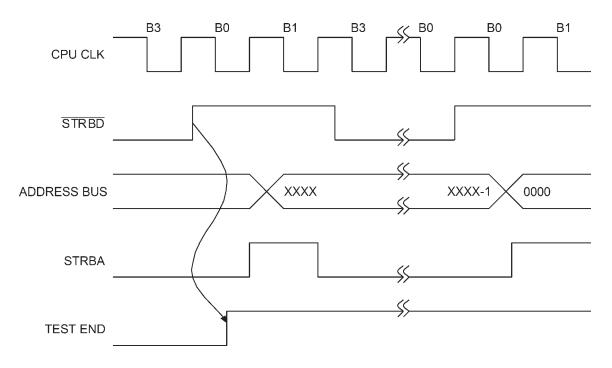
All time measurements on active signals relative to 1.5V levels.



## **RDYD TIMING**



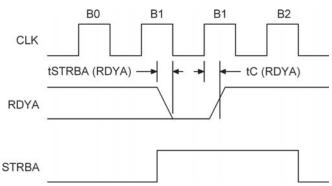
## **TEST END TIMING<sup>1</sup>**



#### Notes:

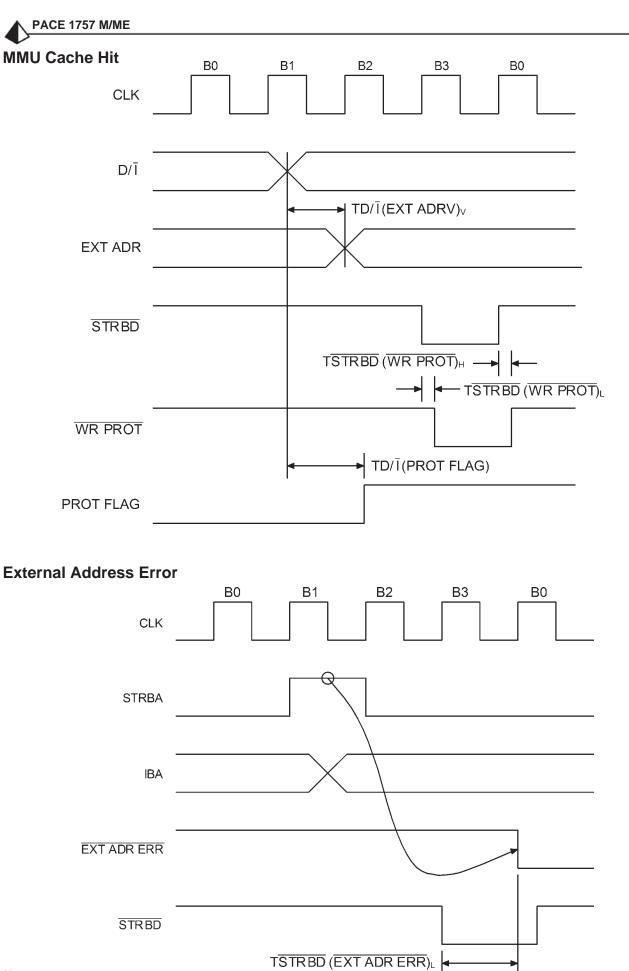
- 1. The last two instructions executed during system test are: XIO RA, 1F44, 0 and JC 7, 0000 hex, 0. After execution of the IOW bus cycle, the XIO proceeds by filling the instruction pipe with two memory read bus cycles where the opcode 7070 hex and 0000 hex are entered to the processor. As from the end of STRBD in the second cycle, TEST END is asserted. At this point, the execution of IC starts by first issuing two fetch cycles from the "old PC" (from addresses XXXX & XXXX +1). The data will be taken from system memory (because TEST END is asserted) but both the address and data are irrelevant. Following that, IC will start filling the pipe from address 0000 hex and 0001 hex, now from the system memory to start user's program execution.
- 2. All time measurements on active signals relate to 1.5V levels.

#### **PACE 1757 M/ME STRT ROM** IB Bus Output (0:15) Β2 STRBD CPU CLK ISTRBD (STRT ROM), ł ł tFC (IB OUT)<sub>v</sub> STRT ROM **IB OUT** EX AD ER **Extended Addresses (0:1)** B1 B2 В3 STRBA CPU CLK tEXT AD (CLKB3) IBA (IN) EXT AD (0:1) IB 16 EXADER IB IN (0:15) tIBA (EX AD ER) tIB IN<sub>v</sub> (IB16) IB 16 **Error Correction (Write Cycle) Memory Protect Error** B3 B0 B1 B2 B0 B1 B2 B3 CLK CLK tIBD<sub>V</sub> (EDC GEN)<sub>V</sub> IBD STRBA tC (MEM PRTERR) EDC GEN MEM PRTERR **Error Correction (Read Cycle) Ready Address** BW1 B2 В3 BW2 B0 B2 B0 B1 B1 CLK ¢ CLK CORRECT tC (IBD CORR) ÇOMBO DATA



### Note:

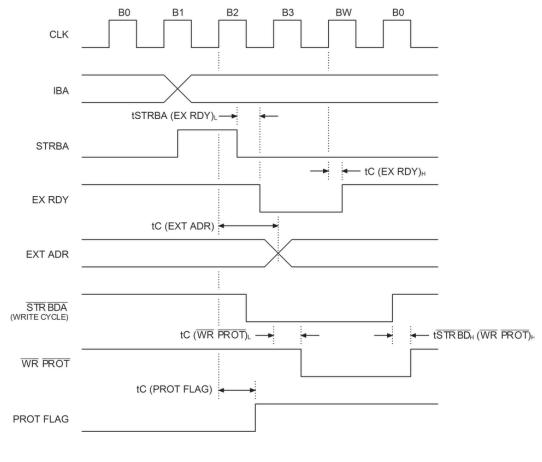
All time measurements on active signals relative to 1.5V levels.



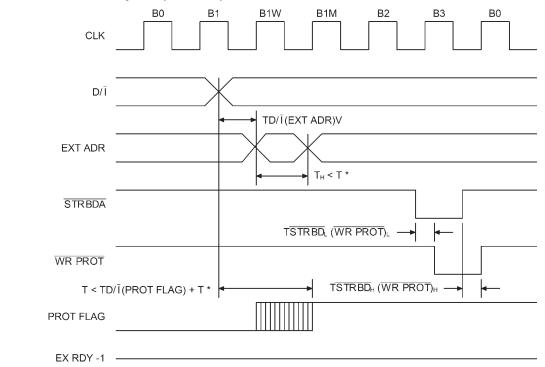
#### Note:

All time measurements on active signals relative to 1.5V levels.

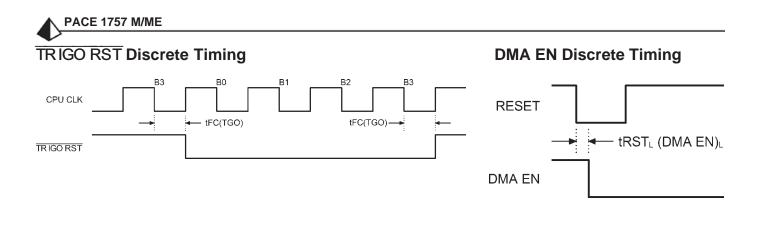
### MMU Cache Miss Cycle (WA = 0)



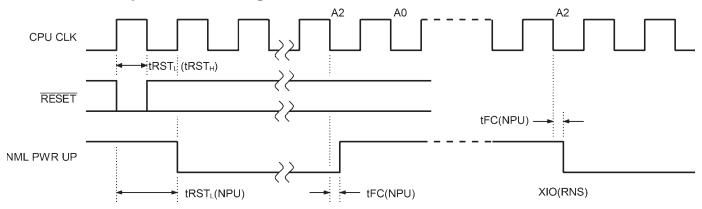
## MMU Cache Miss Cycle (WA > 0)



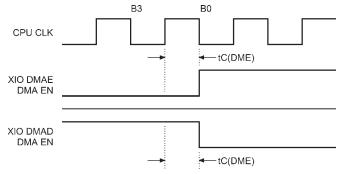
\* The WR PROT/PROT FLAG signal is programmed as WR PROT or PROT GLAG. (See BPU Description). T = 1 Clock Period. **Note**: All time measurements on active signals relate to 1.5V levels.

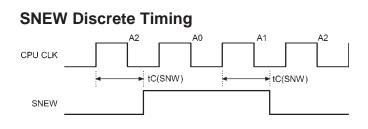


**Normal Power Up Discrete Timing** 



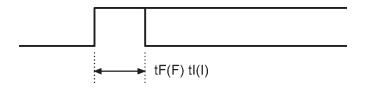
**XIO Operations** 



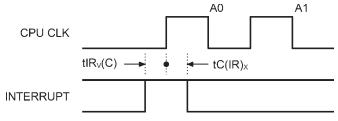


## **External Faults and Interrupts Timing**

# Edge-sensitive interrupts and faults (SYSFLT<sub>0</sub>, SYSFLT<sub>1</sub>) min. pulse width

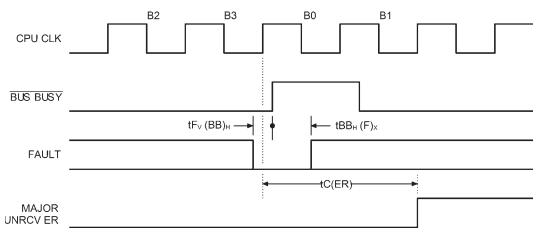


## Level-sensitive interrupts

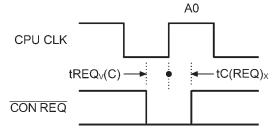




## Level-sensitive faults



### CON REQ

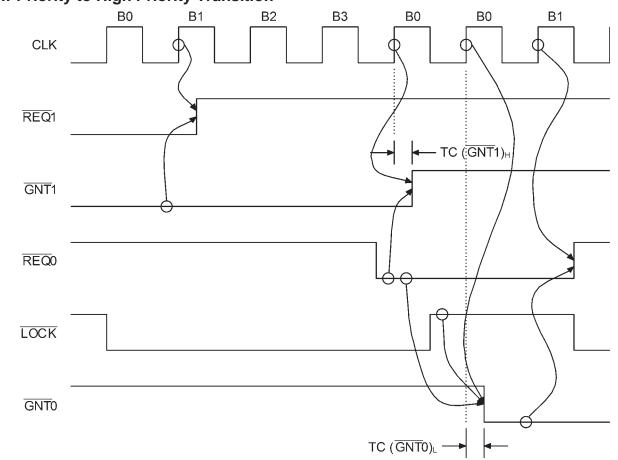


#### Note:

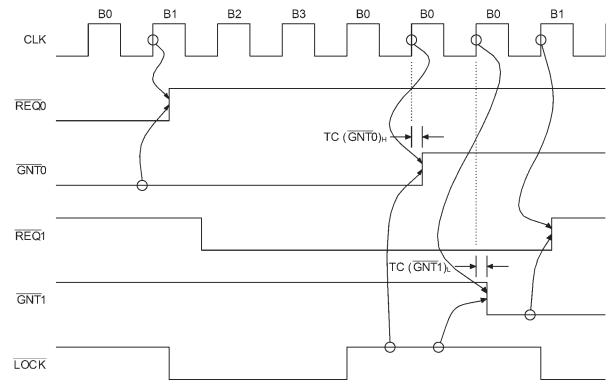
All time measurements on active signals relative to 1.5V levels.

PACE 1757 M/ME

## Low Priority to High Priority Transition

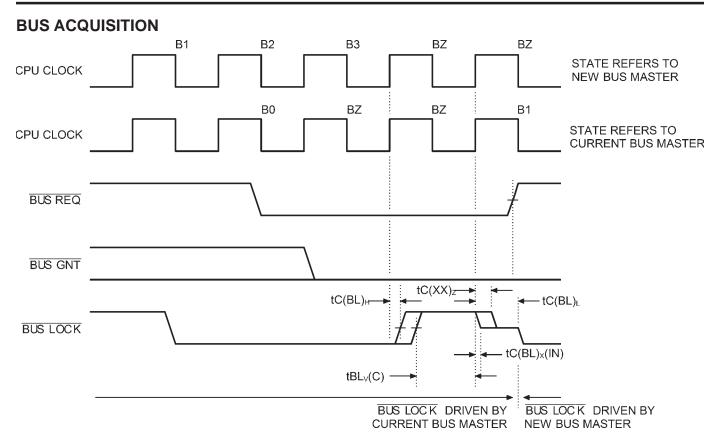


## Bus Arbitrator High Priority to Low Priority Transition



#### Note:

All time measurements on active signals relative to 1.5V levels.

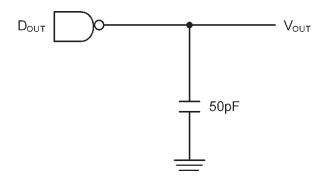


#### Note:

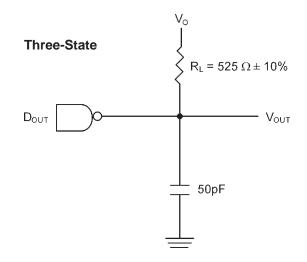
A CPU contending for the BUS will assert the BUS REQ line, and will acquire it when BUS GNT is asserted and the BUS is not locked (BUS LOCK is HIGH).

## SWITCHING TIME TEST CIRCUITS

### Standard Output (Non-Three-State)



Parameter	Vo	V <sub>MEA</sub>
t <sub>PLZ</sub>	≥ 3V	0.5V
t <sub>PHZ</sub>	0V	V <sub>CC</sub> – 0.5V
t <sub>PXL</sub>	V <sub>CC</sub> /2	1.5V
t <sub>PXH</sub>	V <sub>CC</sub> /2	1.5V





## SIGNAL DESCRIPTIONS

### **CLOCKS AND EXTERNAL REQUESTS**

Mnemonic	Name	Description
CPU CLK	CPU clock	A single phase input clock signal (0-40 MHz, 40 percent to 60 percent duty cycle. This is a common input to all 3 devices.
RESET	Reset	An active LOW input that initializes the device. Input to the P1750A/AE, P1753 and P1754.
CON REQ	Console request	An active LOW input that initiates console operations after completion of the current instruction. Input to the CPU.

### **INTERRUPT INPUTS**

Mnemonic	Name	Description
PWRDN INT	Power down interrupt	An interrupt request input that cannot be masked or disabled. This signal is active on the positive going edge or the high level, according to the interrupt mode bit in the configuration register of the P1750A/AE.
USR <sub>0</sub> INT - USR <sub>5</sub> INT	User interrupt	Interrupt request input signals that are active on the positive going edge edge or the high level, according to the interrupt mode bit in the configuration register of the P1750A/AE.
IOL <sub>1</sub> INT - IOL <sub>2</sub> INT	I/O Level Interrupts	Active HIGH interrupt requests that can be used to expand the number of user interrupts. Inputs to the P1750A/AE interrupt register.

### **ERROR CONTROL**

Mnemonic	Name	Description
UNRCV ER	Unrecoverable error	An active HIGH output that indicates the occurrence of an error classified as unrecoverable. A signal from the CPU.
MAJ ER	Major error	An active HIGH output that indicates the occurrence of an error classified as major. A signal from the CPU.

### **DISCRETE CONTROL**

Mnemonic	Name	Description
NML PWRUP	Normal power up	An active HIGH output that is set when the CPU has successfully completed the built-in self test in the initialization sequence. It can be reset by the I/O command RNS.
SNEW	Start new	An active HIGH output that indicates a new instruction is about to start executing in the next cycle. This signal is issued by the CPU.
TR IGO RST	Trigger-go reset	An active LOW discrete output. This signal can be pulsed low under program control I/O address 400B (Hex) and is automatically pulsed during processor initialization.
STRT ROM	Start Up Rom	An output follow the execution of the ESUR and DSUR, I/O commands as defined in MIL-STD-1750A. It will be at the logical level "1" after executing ESUR and at the logical "0" level after executing DSUR. Initially, it defaults to a "1" on the P1754.
DMA EN	Direct memory Access enable	An active HIGH output that indicates the DMA is enabled. It is disabled when the CPU is initialized (reset) and can be enabled or disabled under program control (I/O commands DMAE, DMAD).

Mnemonic	Name	Description
TEST ON	System Test Enable	An active-LOW input, used to enable the execution of the System Test built into the P1754, immediately after completetion of the PACE 1750 A/ AE initialization and before fetching any instructions from the user's program.
TEST END	System Test End	An active-HIGH output indicating whether the PACE 1754 System Test has been completed. Whenever the System Test is disabled by the $\overline{\text{TEST}}$ ON signal, the TEST END output will be at a logical "1" immediately after reset is removed.
SC <sub>0</sub> -SC <sub>4</sub>	System Configuration Inputs	Inputs which are buffered onto IB0-IB4 when executing an I/O Read from I/O address 8410 (hex).
D/Ī	Data or instruction	An output signal that indicates whether the current bus cycle access is for Data (HIGH) or Instruction (LOW). It is three-state during bus cycles not assigned to the CPU. This line can be used as an additional memory address bit for systems that require separate data and program memory.
R/W	Read or write	An output signal that indicates direction of data flow with respect to the current bus master. A HIGH indicates a read or input operation and a LOW indicates a write or output operation. The signal is three-state during bus cycles not assigned to the CPU.
M/ĪO	Memory or I/O	An output signal that indicates whether the current bus cycle is memory (HIGH) or I/O (LOW). This signal is three-state during bus cycles not assigned to the CPU.
RDYA_IN	Address ready In	An active HIGH input to the CPU that can be used to extend the address phase of a bus cycle. When RDYA_IN is not active, wait states are inserted by the P1750A/AE to accomodate slower memory or I/O devices. This line is usually connected to RDYA_OUT unless the memory interface logic requires the two RDYA signals remain discrete as an input and output.
RDYA_OUT	Address Ready Out	An active HIGH output from the COMBO that indicates that there are no wait states requested when STRBA is active. Wait states are inserted when this signal becomes inactive during STRBA. Up to 3 wait states can be inserted by programming an internal register. Three wait states are inserted after reset (default).
RDYD	Data ready	An active HIGH signal to the CPU from the PIC that extends the data phase of a bus cycle. When RDYD is not active, wait states are inserted by the P1750A/AE to accomodate slower memory or I/O devices.

## **BUS ARBITRATION**

Mnemonic	Name	Description
BUS REQ	Bus request	An active LOW output that indicates the CPU requires the bus. It becomes inactive when the CPU has acquired the bus and started the bus cycle.
BUS GNT	Bus grant	An active LOW input from an external arbiter that indicates the CPU currently has the highest priority bus request. If the bus is not used and not locked, the CPU may begin a bus cycle, commencing with the next CPU clock. A HIGH level will hold the CPU in Hi-Z state (Bz), three-stating the IB bus status lines (D/ $\bar{I}$ , R/ $W$ , M/ $\bar{IO}$ ), strobes (STRBA, STRBD), and all the other lines that go three-state when this CPU does not have the bus.
BUS BUSY	Bus busy	An active LOW, bidirectional signal used to establish the beginning and end of a bus cycle. The trailing edge (LOW-to-HIGH transition) is used for sampling bits into the fault register. It is three-state in bus cycles not assigned to this CPU. However, the CPU monitors the BUS BUSY line for latching non-CPU bus cycle faults into the fault register.
BUSLOCK	Bus lock	An active low, bi-directional signal used to lock the bus for successive bus cycles. During non-locked bus cycles, the BUS LOCK signal mimics the BUS BUSY signal. It is three-state during bus cycles not assigned to the CPU. The following instructions will lock the bus: INCM, DECM, SB, RB, TSB, SRM, STUB and STLB.
$\frac{BUS \ GNT_0}{BUS \ GNT_3}$	Bus Grant	Active-LOW outputs from the PIC indicating which master was granted the BUS. It remains active during BUS LOCK unless a higher master request occurs, which resets it. However, the higher master will be granted the BUS only after the current master's BUS LOCK releases the BUS.
BUS REQ <sub>0</sub> - BUS REQ <sub>3</sub>	Bus Request	Active-LOW inputs to the PIC that indicate a requirement for the BUS from the 4 masters on the bus. The master assigned to pin $\overline{\text{BUS REQ}}_0$ has the highest priority. The master assigned to pin $\overline{\text{BUS REQ}}_3$ has the lowest priority.

## FAULTS AND FLAGS

Mnemonic	Name	Description
MEM PRT ER	Memory Protect Error	An active-LOW input generated by the MMU or BPU, or both, during attempted writes to protected memory. It is sampled by the BUS BUSY signal into the Fault Register (bit 0 CPU bus cycle, bit 1 if non-CPU bus cycle). The error is generated in one of the following conditions: a mismatch in the access keys in the MMU page, an access to an execution protected page during instruction cycles, an access to a write protected page during data cycles or an access to a page write protected by the BPU.
MEM PAR ER	Memory Parity Error	An active LOW signal which is sampled by the BUS BUSY signal into bit 2 of the CPU's Fault Register. It signals an error on the Data Bus during a memory cycle. Two detection modes can be selected by programming the control register of the MMU/COMBO: EDAC mode (6 Hamming code parity bits) or single bit parity mode (even or odd parity). The signal is inactive when none of the above modes are selected (default after reset).
EXT ADR ER IN	External Address Error In	An active-LOW input sampled by the $\overline{\text{BUS BUSY}}$ signal into the CPU Fault Register (bit 5 or 8) depending on the cycle (memory or I/O).
EXT ADR ER OUT	External Address Error Out	An active LOW output which signals to the CPU and memory interface logic that an unimplemented memory or illegal I/O access has taken place.
SYSFLT <sub>0</sub> - SYSFLT <sub>1</sub>	System Fault 0, System Fault 1	Asynchronous, positive edge sensitive inputs that set bit 7 (SYSFLT <sub>0</sub> ) or bits 13 and 15 (SYSFLT <sub>1</sub> ) in the P1750A/AE Fault Register.
EX AD ER 7 SING ERR	Illegal Address Error / Single Error	An active LOW output from the PIC indicating an illegal address error when referencing memory or I/O. It becomes an active HIGH input called SINGLE ERROR for handshaking with the P1753 when the PIC is programmed to support EDAC. Default state after reset is high impedance.
WR PROT / PROT FLAG	Write Protected / Protection Flag	Either an active LOW output (WR PROT, following STRBD timing) during legal memory write cycles when no protection occurs, or an active high (PROT FLAG) signal indicating a protection error in a write cycle. Either mode can be selected by programming the COMBO control register. Default mode after reset is Write Protected.
ME PA ER 7 RAMDIS	Memory Parity Error	An active LOW output indicating a Parity error when reading from memory. It becomes an active HIGH output called RAM DISABLE for handshaking with the P1753 when the PIC is programmed to support EDAC.
тс	Terminal Count	An active HIGH output from the PIC indicating a bus time out or a watchdog trigger.



## **PACE 1757 M/ME**

## SIGNAL DESCRIPTIONS (Continued)

## STATUS BUS

Mnemonic	Name	Description
АК <sub>0</sub> - АК <sub>3</sub>	Access key	Active HIGH outputs corresponding to the AK field of the processor status word used to match the Access Lock in the MMU for memory accesses (a mismatch will cause the MMU to pull the $\overline{\text{MEM PRT ER}}$ signal LOW), and also indicate the processor state (PS). Priveledged instructions can be executed with PS=0 only. These signals are tri-state for bus cycles not assigned to this CPU
AS <sub>0</sub> - AS <sub>3</sub>	Address state	Active HIGH outputs corresponding to the AS field of the processor status word that selects the page register group in the MMU. In the DMA physical demultiplexed mode, AS(0:1) will receive the 9th and 10th most significant bits of the physical address for use in the BPU function. These signals are tri-state in bus cycles not assigned to this CPU.

### **INFORMATION BUS**

Mnemonic	Name	Description
IB <sub>0</sub> - IB <sub>15</sub>	Information bus	A bi-directional time-multiplexed address/data BUS. $\ensuremath{IB}_0$ is the most significant bit.
EDC <sub>0</sub> -EDC <sub>5</sub>	Error Detection / Correction Bus	An active HIGH output BUS used for detection of errors on the data BUS $(IB_0-IB_{15})$ and correction of single errors. When working in parity mode $EDC_0$ is the parity bit. $EDC_1-EDC_5$ are undefined in this case.
Ā(0:1)7 EXT ADR(0:1) A(2:15)	Address Bus	An active HIGH output BUS from the PIC. Contains the address of the current bus cycle as latched by the end of STRBA. In system configurations including the MMU function, the only active lines during memory cycles are A(4:15). In this example, A(2:3) are high impedance (don't care) and A(0:1) turn into inputs called Extended Addresses, EXT AD (0:1). In this situation, these two lines, supplied by the MMU, will be used to operate the programmable ready generation during bus cycles.
EXT ADR <sub>0</sub> - EXT ADR <sub>7</sub>	Extended Address Bus	A bi-directionaly active HIGH BUS. In CPU cycles, it is an output BUS that is used to select one of 256 pages, 4K words each, expanding the direct addressing space to 1M word. In DMA cycles, indicated by DMA-ACK being active, it is also an output BUS except when programmed for the physical demultiplexed DMA mode. In this example, it becomes an input to receive the eight most significant bits of the DMA physical address for use in the BPU function.

<b>BUS STROBES AND</b>	
DUS STRUDES ANL	QUALIFIERS

Mnemonic	Name	Description
STRBA (note 1)	Address Strobe	An active HIGH output that can be used to externally latch the contents of IB(0:15) into the address latches of the PIC and MMU at the HIGH to LOW transition of the strobe. The signal is tristate during bus cycles not assigned to this CPU. It is issued by the CPU and input to the MMU and PIC.
STR BD (note 2)	Data Strobe	An active LOW output used to read or write data from the PIC as well as to strobe data in memory and XIO cycles. This signal is tri-state during bus cycles not assigned to this CPU. It is interconnected in the same manner as STRBA.
MEMW	Memory Write Strobe	An active LOW output produced in memory write cycles by the PIC.
MEMR	Memory Read Strobe	An active LOW output produced by the P1754 in memory read cycles.
ĪOW	I/O Write Strobe	An active LOW output produced by the P1754 in output write cycles.
ĪOR	I/O Read Strobe	An active LOW output produced by the P1754 during input read cycles.
STRBEN	Strobe Enable	An active LOW input, enabling the active state of the address outputs of the P1754 and the MEMR, MEMW, IOR and IOW outputs. When a logic "1" (if enabled by bits EST and EAD of the control register) it will correspondingly tri-state the above signals.
INTA	Interrupt Acknowledge Strobe	An active LOW output produced during any interrupt sequence corresponding to an output write to address 1000 (Hex).
DMA ACK	DMA Acknowledge	An active HIGH input from the DMA controller to the P1753 which indicates a DMA cycle. Used to select the DMA table in the BPU memory for protection. For example, this could allow the DMA channel to update the program which could be write protected from the processor. In the physical DMA mose, it will cause the Extended Address Liones (EXT ADR <sub>0-7</sub> ) to become inputs providing BPU protection of the DMA transfers.
EX RDY	External Data Ready	An active HIGH output from the MMU that indicates no wait states are requested. It becomes inactive for one clock (inserting one wait state) whenever a memory page different than the current one is accessed (e.g. a cache miss).
EX RDY1	External Data Ready 1	An active LOW input to the PIC from the memory interface logic which at a logical "1" overrides the internal RDYD generation and forces it to a logical "0".

Note 1: One internal pulldown resistor is provided at the STRBA input. The nominal value is 40K Ohm and the maximum range is 20K Ohm to 80K Ohm. In designs with TTL devices loading STRBA, an additional external resistor may be required.

Note 2: One internal pullup is provided at the STRBD input. The nominal value is 40K Ohms and the maximum range is 20K-80K Ohms.

## COMBO REGISTER MAP

CONT	ROL RE	GISTE	R (1F50	/9F50)											
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
QR1	QR2	QR3	QR4	ODD	EEI	EED	EPR	SPD	WPT	EB1	EB2	EIO	GPT	DMX	DLP
														I	
CONTR	ROL RE		•	51/9F51											
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
WA0	WA1	SPI	RES*	PEG	IDL					RESE	RVED				
	PLEMEN					(1F55/9	F55)								
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
			BL1	LO							BL1	I HI			
,															
	PLEMEN					•			-						
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
			BL2	LO							BL2	2 HI			
	UNIMP					•				4.0		10	4.0		4 -
0	1	2	3	4	5	6	7	-	9	10	11	12	13	14	15
Х	Х	Х	Х	Х	Х		L	ASTS	EQUEN	HAL PI	0 0011	OI CO	MMANI		
		LEMEN 2	TED IN 3						0	10	11	10	10	4.4	15
0	1			4	5	6	7	8	9			12	13	14	15
Х	Х	Х	Х	Х	Х			LASIS	SEQUE	NHAL P			IMAND		
FIDOT						50)									
0	FAILIN	<b>G ADD</b>	8 <b>635 F</b> 3	4	<b>ЕК (9F</b> : 5	<b>6</b>	7	8	9	10	11	12	13	14	15
0	I	Z	3	-		ING PH						12	15	14	10
				FIRC			TSICAL	. ADDR	E33 - F	ADR (4	+. 19)				
FIDET				STED (											
0	FAILIN	2 g DAT	3	31ER (: 4	<b>эгэа)</b> 5	6	7	8	9	10	11	12	13	14	15
			0	-1	5	0	-				11	14	10	14	15
	I	_				FIRCT			WODD						
	I	_				FIRST	FAILING	6 DATA	WORD						
				FGIET			FAILING	) DATA	WORD						
<b>MEMO</b> 0	RY FAL		ATUS R 3	EGIST			FAILING	B DATA	WORD	10	11	12	13	14	15

\* Reserved

## COMBO REGISTER MAP DEFINITIONS

### **CONTROL REGISTER (1F50/9F50)**

(Default = 00C6H)

(Defau	JIt = 00C6H)
QR1	Enable error detection/correction or parity
	checking/generation for memory addresses 00000H-3FFFFH.
QR2	Enable error detection/correction or parity
	checking/generation for memory addresses 40000H-7FFFFH
QR3	Enable error detection/correction or parity
	checking/generation for memory addresses 80000H-BFFFFH.
QR4	Enable error detection/correction or parity
	checking/generation for memory addresses C0000H-FFFFFH.
ODD	Enable odd parity, 1 = ODD, 0 = EVEN
EEI	Enable error detection/correction (EDAC) on
	instruction fetch only.
EED	Enable error detection/correction (EDAC) on operand (data) fetch only.
EPR	Enable parity detection function. (If both
	EPR and either EEI or EED are enabled, EEI
	or EED will take preference.)
SPD	Enable 1 wait state on MMU cache miss
	cycle (1 = 1 WAIT, 0 = NO WAIT).
WPT	Enable protected write strobe (WR PROT PIN).
	1: WR PROT = write protected strobe
	0: WR PROT = write protect level
	<pre>(1 = write protect memory)</pre>
EB1	Enable block 1 of unimplemented memory
	(as defined in unimplemented memory
	register 1).
EB2	Enable block 2 of unimplementd memory (as
	defined in unimplemented memory register 2).
EIO	Enable illegal PIO detection (as defined in
LIC	last implemented input and output registers,
	and MIL-STD-1750A reserved I/O space).
GPT	Enable global memory protect (Set by
	RESET, and reset by I/O command 4003).
DMX	Demultiplexed Address/data Bus in DMA
2	cycles.
DLP	Logical/Physical DMA (1 = LOGICAL, 0 =
	Physical).

### **CONTROL REGISTER 1 (1F51)**

(Default = C3FFH)

WA0/	Number of WAIT STATES on RDYA
WA1	
SPI	Enable illegal PIO detection for MIL-
	STD1750A spare I/O spaces.

- PEG Determines what is generated when both EDAC and parity checks are disabled.
- IDL Enables/disables the generation of an idle cycle betwee BUS REQ and BUS GNT, during read cycles, allowing for one additional clock cycle to release the IB.

### **UNIMPLEMENTED MEMORY REGISTER 1 (1F55)**

BL1 LO Low boundary of unimplemented block 1 of
memory.

BL1 HI High boundary of unimplemente block 1 of memory.

### **UNIMPLEMENTED MEMORY REGISTER 2 (1F56)**

BL2 LO	Low boundary of unimplemented block 2 of
BL2 HI	memory. High boundary of unimplemented block 2 of
	memory.

### FIRST UNIMPLMENTED OUTPUT COMMAND REGISTER (1F57)

BITS 0:5	Not used.
BITS 6:15	First unused sequential PIO output
	command.

# FIRST UNIMPLMENTED INPUT COMMAND REGISTER (1F58)

BITS 0:5	Not used.
BITS 0:6	First unused sequential PIO input
	command.

### FIRST FAILING ADDRESS REGISTER (1F59)

PADR (4:19) 16 LSB of the physical address of the first failure.

### FIRST FAILING DATA REGISTER (1F5B)

BITS 0:15	"1" indicates the position of the wrong/
	corrected bit in the data word.

### MEMORY FAULT STATUS REGISTER (A00D)

- LPA Page address within the group.
- ID Instruction/data
- AS Group address.



## **PIC REGISTER MAP**

CONT	CONTROL REGISTER (1F40, 9F40)														
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
PR1	PR2	PR3	PR4	ODD	EST	EAD	EXR	SPI	CNF	EB1	EB2	EIO	LIO	LME	0
STATI 0	JS REG	1STER 2	(9F41) 3	4	5	6	7	8	9	10	11	12	13	14	15
CPU	CMB	PIC	-	RVED	STB	ADR	TWD	TBT				RVED			IFL
								1						I	
	ORY REA											10			
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
	MEN	/I Q1			MEN	/I Q2			MEN	/I Q3			MEN	/I Q4	
I/O RE				STFR (	1F43 0	(F43)									
0	1		3	4	5	6	7	8	9	10	11	12	13	14	15
	IO	Q1			IO	Q2			IO	Q3			IO	Q4	
L								1				1			I
	RAM RE		•	. ,			_					10	10		
0	1	2		4	5	6	7	8	9	10	11	12	13	14	15
	CLUCK	FREG	UENCY	′ (MHZ)		EBT	SBT	EWD	SWD			RESE	RVED		
WATC	H DOG	TIMER	(1F45	9F45)											
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
						WATCH	HDOG S	SETUP	COUNT						
	PLEMEN				•			0	0	10		10	10		4.5
0	1	2	3	4	5	6	7	8	9	10 2 LO	11	12	13	14	15
	BLI	LO			BL	1 HI			BL2				BL	2 HI	
FIRST					сомм		F47 9F	(47)							
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
Х	Х	Х	Х	Х	Х		F	IRST UI	NIMPLE	MENT	ED OUT	PUT CO	OMMAN	ID	
L															
	UNIMP							,	-						
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
Х	Х	Х	Х	Х	Х			FIRST	JNIMPL	EMEN	red inf	UT CO	MMANE	)	
FIPST	FAILIN	ם מש		FGIGT		10)									
0	1	2 2	3	4	5 EK	<b>+9)</b> 6	7	8	9	10	11	12	13	14	15
							FAILIN	IG ADD	RESS						
L															

## PIC REGISTER MAP DEFINITIONS

### CONTROL REGISTER (Default = 0000)

	ROL REGISTER (Default = 0000)
PR1	Enable Parity Checking/Generation for
	Memory Addresses 0000-3FFF.
PR2	Enable Parity Checking/Generation for
	Memory Addresses 4000-7FFF.
PR3	Enable Parity Checking/Generation for
	Memory Addresses 8000-BFFF.
PR4	Enable Parity Checking/Generation for
	Memory Addresses C000-FFFF.
ODD	Enable ODD Parity.
EST	Enable Three State Control on PIC
	Generated Strobes: IOR, IOW, MEMR,
	MEMW.
EAD	Enable Three State Control on PIC
	Generated Address: A <sub>0</sub> -A <sub>15</sub> .
EXR	Extends ready generation over the full I/O
	space when = 1. (Default = 0)
SPI	Enables IILEGAL PIO detection for MIL-STD-
	1750A spare I/O spaces. 1 = Spare I/O legal,
	0 = Default = spare I/O illegal.
CNF	EDAC Function on MMU/COMBO; 1 = used,
	0 = not used.
EB1	Enable Block 1 of Unimplemented Memory,
	as Defined in the Unimplemented Memory
	Register.
EB2	Enable Block 2 of Unimplemented Memory,
	as Defined in the Unimplemented Memory
	Register
EIO	Enable illegal PIO Detection, as defined in
	Last Implemented Input and Output
LIO	Registers. Enable Long I/O Ready Generation, 1ms to
	15ms, I/O Addresses 0000-00FF, 8000-
	80FF.
LME	Enable Long Memory Ready Generation,
	1ms to 15ms, Addresses 0000-3FFF.
	1115 to 15115, Addresses 0000-3177.

### **STATUS REGISTER** (Default = 0000)

CPU CPU Passed PIC System Test.

- CMB COMBO Chip Passed PIC System Test.
- PIC PIC Chip Passed PIC System Test.
- STB Reserved.
- ADR Reserved.
- TWD Watch Dog reached terminal count.
- TBT Bus Time-out reached terminal count.
- IFL Interrupt Flag-Shows the last interrupt I/O command implemented in the software.

## MEMORY READY PROGRAM REGISTER

### (Default = FFFF)

MEM Q1	Lower Block number of wait states.
MEM Q2	Second Block number of wait states.
MEM Q3	Third Block number of wait states.
MEM Q4	Upper Block number of wait states.

### I/O READY PROGRAM REGISTER

(Default = Undefined)

PROCEAM RECISTER (Default - 0000)				
IO Q4	Upper section number of wait states.			
IO Q3	Third section number of wait states.			
IO Q2	Second section number of wait states.			
IO Q1	Lower section number of wait states.			
(	/			

### **PROGRAM REGISTER** (Default = 0000)

CFB	0:5, Clock Frequency Bits (MHz).
EBT	Enable Bus Time-out Function.
SBT	Select Bus Time-out Limit; 1 = 128
	Cycles, 0 = 64 Cycles.
EWD	Enable Watch Dog Function.
SWD	Select Watch Dog Clock, 1 = 1KHz, 0 =
	1MHz.

WATCH DOG TIMER REGISTER (Default = 0000)

BITS 0:15, Watch Dog set-up Count.

## UNIMPLEMENTED MEMORY REGISTER

(Default = Undefined)

,	•
BL1 LO	Low boundary of unimplemented block
	1 of memory.
BL1 HI	High boundary of unimplemented block
	1 of memory.
BL2 LO	Low boundary of unimplemented block
	2 of memory.
BL2 HI	High boundary of unimplemented block
	2 of memory.
	-

### FIRST UNIMPLEMENTED OUTPUT COMMAND

**REGISTER** (Default = Undefined)

BITS 0:5Not used.BITS 6:15First unused sequential PIO output<br/>command.

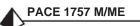
### FIRST UNIMPLEMENTED INPUT COMMAND

**REGISTER** (Default = Undefined)

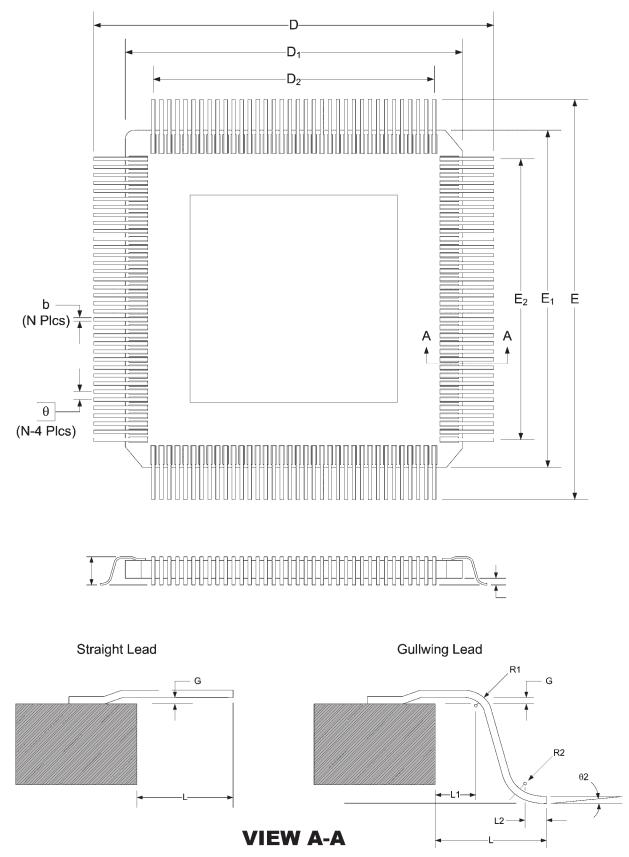
BITS 0:5	Not used.
BITS 6:15	First unused sequential PIO input
	command.

### FIRST FAILING REGISTER (Default = Undefined)

BITS 0:15 16 LSB of the physical address of the first failure.



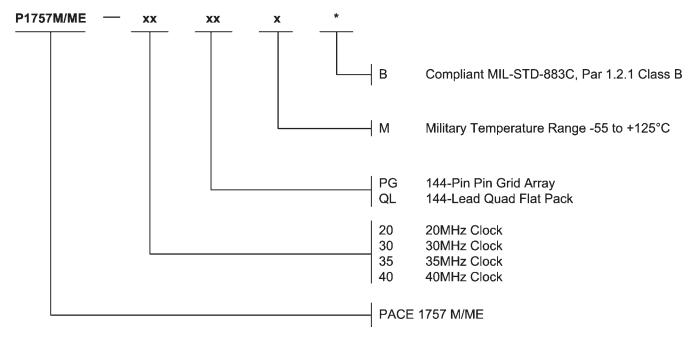
## PACKAGE OUTLINE



## 1757M/ME 144-LEAD QUAD FLATPACK OUTLINE

	Straight Leads		Gullwing Leads	
Α	130	± 10	175	± 20
A1	N/A		25	±5
b	8	± 2	8	± 2
с	6	± 2	6	±1
D	1850	± 15	1450	± 10
D1	1150	± 12	1150	± 12
D2	875	REF	875	REF
Е	1750	± 5	1450	± 10
E1	1150	± 12	1150	± 12
E2	875	REF	875	REF
L1	N/A		75	± 15
L2	N/A		25	±5
L	300	± 5	150	± 10
R1	N/A		25	±2
R2	N/A		25	±2
O1	N/A	± 4	0°	7°
O2	N/A		0°	7°
G	8		8	± 4
Ν	144		144	

## **ORDERING INFO**



## REVISIONS

DOCUMENT NUMBER: DOCUMENT TITLE:		MICRO-10 PACE1757M/ME COMPLETE EMBEDDED CPU SUBSYSTEM	
REV.	ISSUE DATE	ORIG. OF CHANGE	DESCRIPTION OF CHANGE
ORIG	May-89	RKK	New Data Sheet
Α	Jul-04	JDB	Added Pyramid logo
В	Sep-05	JDB	Re-created electronic version